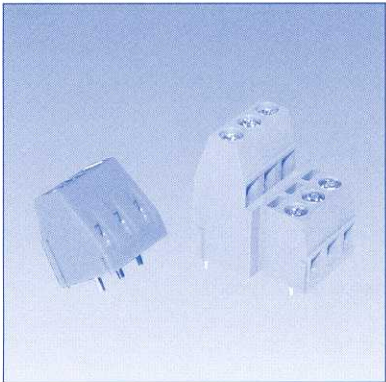




Application and Features:

- The Nextron Multi-level Series offers 5.0mm, 5.08mm pin spacing. These series are designed in single level, bi-level and tri-level interlockable housings of the same pitch.
- Designed as a solution for limited space on the PC Board, the Multi-level series offers end to end stackability with snap together and stay together design.

Technical Data:

Material:

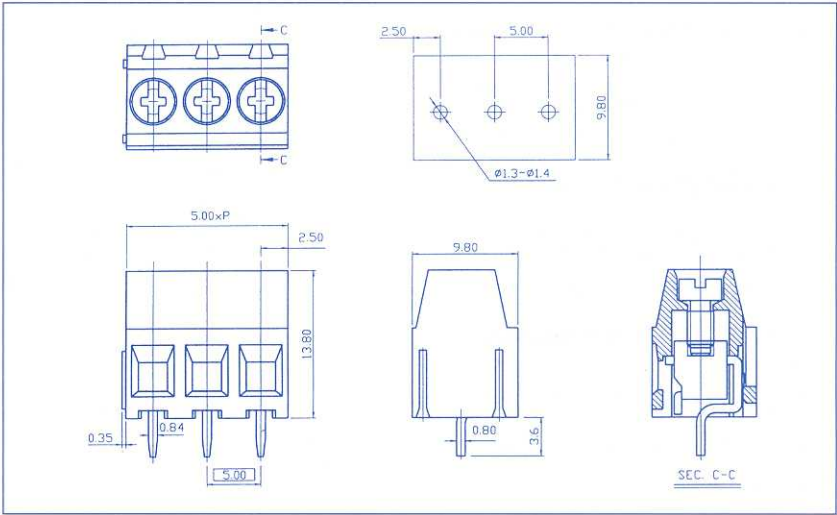
- HOUSING: NYLON (Glass Filled) UL 94V-0.
- Metal Housing: Brass Ni50u" + SnPb120u", plated.
- Screw: Steel, Zinc Plated. M2.6.*0.45

Electrical:

- Current rating: 10 Amps / way (Max).
- Insulation resistance: 500M Ω (Min) / DC500V.
- Withstanding Voltage: 2000VAC (minute). test time= 60sec / 1pcs.
- Operation voltage: 300 VAC.
- Wire Range: 12-24 AWG.

Mechanical:

- Tightening Torque: 4 Kg-cm (Max).
- Operating temperature: -55°C to +105°C
- Solderability: 95 % coverage (Min). test temperature= 230°C $\pm$ 10°C. test time= 3sec $\pm$ 0.5sec.



Notes: Please replace 'X' with appropriate coding listed in the tables below

3 4 0 - X X X - X X 0 0

Number of contact

02-24 po	02
	03
	etc.

Pitch

5.00mm/.197"	1
10.00mm/.394"	2
5.08mm/.200"	A
10.16mm/.400"	B

Housing Selection

SINGLEL	0
BI-LEVE	1
TRI-LEVEL	2
SINGLE+BI- LEVEL	3
BI-LEVEL+TRI-LEVEL	4
SINGLE+BI-LEVEL+TRI-LEVEL	5

Color

Green	5
Blue	6
Gray	8